

## Patent Abstracts of Japan

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TITLE : EPOXY RESIN COMPOSITION

ABSTRACT : PURPOSE: The titled composition excellent in electrical insulation and suitable for sealing electrical parts, etc., obtained by mixing an epoxy resin with an epoxy resin curing agent having a plurality of phenolic hydroxyl groups in the molecule, a fluorocarbon and a cure accelerator.

CONSTITUTION: The purpose epoxy resin composition is prepared by mixing (A) an epoxy resin consisting mainly of a novolak epoxy resin of an epoxy equivalent of 170~300 with (B) an epoxy resin curing agent having at least two phenolic hydroxyl groups in the molecule (e.g., novolak phenolic resin), 0.01~10wt%, based on component A, (C) fluorocarbon, and 0.01~20wt% based on the total of components A and B, (D) cure accelerator (e.g., triphenylphosphine) in such amounts that the ratio of the number of the phenolic hydroxyl groups of component B to that of the epoxy groups in component A is 0.5~1.5.

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